



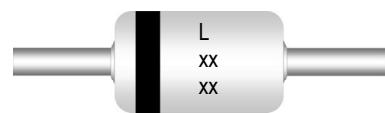
SEMICONDUCTOR

500 mW DO-35 Hermetically Sealed Glass Fast Switching Diodes



**AXIAL LEAD
DO35**

DEVICE MARKING DIAGRAM



L : Logo
TC1Nxxxx : Device Code

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
P _D	Power Dissipation	500	mW
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _J	Operating Junction Temperature	+150	°C
W _{IV}	Working Inverse Voltage	75	V
I _o	Average Rectified Current	150	mA
I _{FM}	Non-repetitive Peak Forward Current	450	mA
I _{FSURGE}	Peak Forward Surge Current (Pulse Width = 1.0 μ second)	2	A

These ratings are limiting values above which the serviceability of the diode may be impaired.

Specification Features:

- Fast Switching Device ($T_{RR} < 4.0$ nS)
 - DO-35 Package (JEDEC)
 - Through-Hole Device Type Mounting
 - Hermetically Sealed Glass
 - Compression Bonded Construction
 - All External Surfaces Are Corrosion Resistant And Leads Are Readily Solderable
 - RoHS Compliant
 - Solder Hot Dip Tin (Sn) Terminal Finish
 - Cathode Indicated By Polarity Band



ELECTRICAL SYMBOL

Electrical Characteristics

$T_A \equiv 25^\circ\text{C}$ unless otherwise noted

Electrical Characteristics		$T_A = 25^\circ C$ unless otherwise noted			Unit	
Symbol	Parameter	Test Condition	Limits			
			Min	Max		
B_V	Breakdown Voltage	$I_R=100\mu A$	100		Volts	
		$I_R=5\mu A$	75			
I_R	Reverse Leakage Current	$V_R=20V$	25	nA	μA	
		$V_R=75V$		5		
V_F	Forward Voltage TC1N4448, TC1N914B TC1N4148 TC1N4448, TC1N914B	$I_F=5mA$	0.62	0.72	Volts	
		$I_F=10mA$		1.0		
		$I_F=100mA$		1.0		
T_{RR}	Reverse Recovery Time	$I_F=10mA, V_R=6V$		4	nS	
		$R_L=100\Omega$				
		$I_{RR}=1mA$				
C	Capacitance	$V_R=0V, f=1MHz$		4	pF	

Typical Characteristics

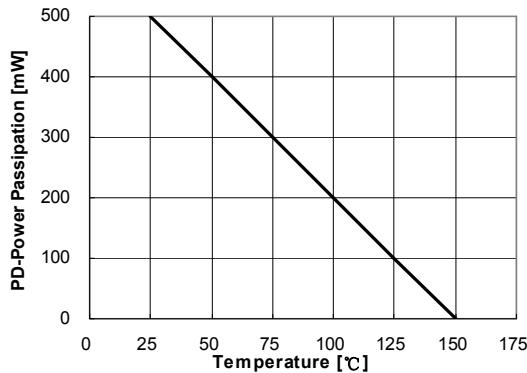


Figure 1. Power Dissipation vs Ambient Temperature
Valid provided leads at a distance of 0.8mm from case are kept at ambient temperature

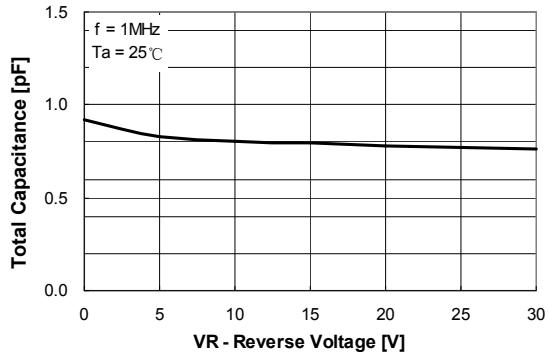


Figure 2. Total Capacitance

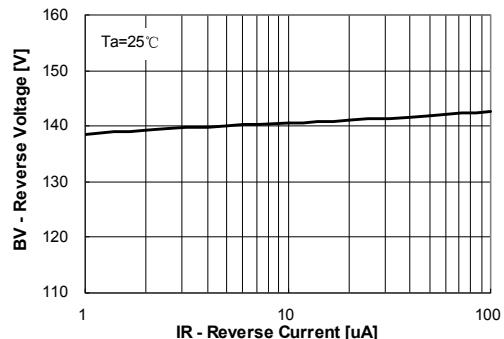


Figure 3. Reverse Voltage vs Reverse Current
BV – 1.0uA to 100uA

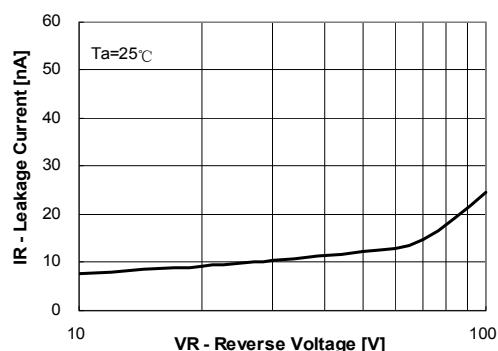


Figure 4. Reverse Current vs Reverse Voltage
IR – 10V to 100V

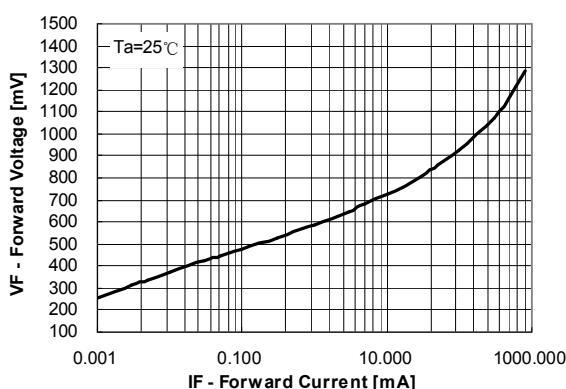


Figure 5. Forward Voltage vs Forward Current
VF – 0.001mA to 800mA

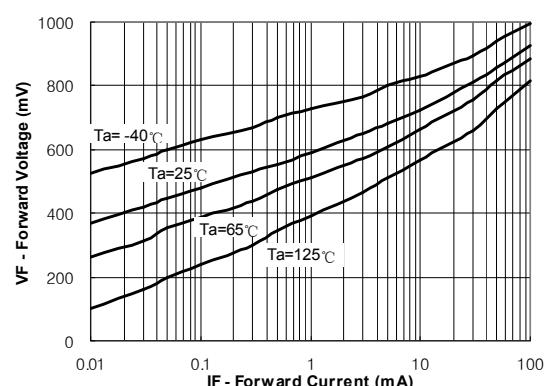
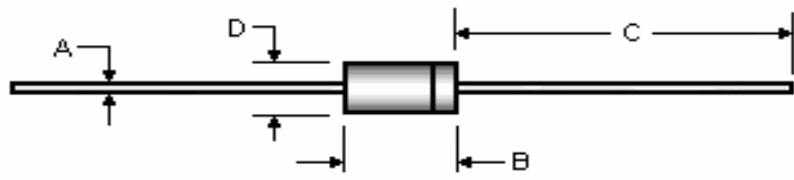


Figure 6. Forward Voltage vs Ambient Temperature
VF – 0.01mA to 100mA (-40 to +125 Deg C)

Package Outline

Package	Case Outline				
DO-35	 DO-35				
	DIM	Millimeters		Inches	
		Min	Max	Min	Max
	A	0.46	0.55	0.018	0.022
	B	3.05	4.00	0.120	0.157
	C	25.40	38.10	1.000	1.500
	D	1.53	2.00	0.060	0.079

Notes:

1. All dimensions are within JEDEC standard.
2. DO35 polarity denoted by cathode band.



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